4 Bill of Materials, Board Layout, and Schematics

4.1 Bill of Materials — bq24300/02/04/10/14/16

	-			-		-	-	1				1	1
b q 2													
4	4	4	4	4	4	4	4						
3	3 0	3 0	3 0	3 1	3 1	3 1	3 1						
Ō	2	4	8	0	2	4	6						
- 0	0	- 0	- 0	- 0	- 0	- 0	- 0						
0 1	0 2	0 3	0 4	0 5	0 6	0 7	0 8	RefDes	Value	Description	Size	Part Number	MFR
1	1	1	1	0	0	0	0	C1	1 μF	Capacitor, Ceramic, 35-V, X7R, 10%	805	Std	Std
1	1	1	1	1	1	1	1	C2	1 μF	Capacitor, Ceramic, 35-V, X7R, 10%	805	Std	Std
3	3	3	3	3	3	3	3	C3–C5	1 μF	Capacitor, Ceramic, 16-V, X7R, 10%	805	Std	Std
1	1	1	1	1	1	1	1	D1	BZT52C5V1S	Diode, Zener, 200mW, 5.1V	SOD-323	BZT52C5V1S	General
4	4	4	4	4	4	4	4	D2, D3, D5, D6	LTST- C190GKT	Diode, LED, Green, 2.1-V, 20-mA, 6-mcd	603	LTST- C190GKT	Liteon
1	1	1	1	1	1	1	1	D4	LTST- C190CKT	Diode, LED, Red, 1.8-V, 20-mA, 20-mcd	603	LTST- C190CKT	Liteon
3	3	3	3	3	3	3	3	J1–J4	ED1514	Terminal Block, 2-pin, 6-A, 3,5mm	0.27 x 0.25 in	ED1514	OST
1	1	1	1	1	1	1	1	J2	ED1516	Terminal Block, 4-pin, 6-A, 3,5mm	0.55 x 0.25 in	ED1516	OST
8	8	8	8	8	8	8	8	JMP1–JMP8	PTC36SAAN	Header, 2-pin, 100mil spacing, (36-pin strip)	0.100 in x 2	PTC36SAAN	Sullins
8	8	8	8	8	8	8	8	JMP1–JMP8	929950-00	Shorting jumpers, 2-pin, 100mil spacing		929950-00	3M/ESD
1	1	1	1	0	0	0	0	Q1	Si2343DS	MOSFET, Pch, –30 V, 4 A, 53 m Ω	SOT23	Si2343DS	Vishay
1	1	1	1	0	0	0	0	R1	100k	Resistor, Chip, 1/16W, 5%	603	Std	Std
0	0	0	0	1	1	1	1	R2	0	Resistor, Chip, 1/8W, 5%	1206	Std	Std
1	1	1	1	1	1	1	1	R3	20k	Resistor, Chip, 1/16W, 5%	603	Std	Std
0	0	0	1	0	0	0	0	R4	113k	Resistor, Chip, 1/16W, 1%	603	Std	Std
0	0	0	0	1	1	1	1	R5	24.9k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	0	1	1	1	1	1	1	R6	100k	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	1	1	1	1	1	1	1	R7	6.2k	Resistor, Chip, 1/16-W, 5%	603	Std	Std
1	1	1	1	1	1	1	1	R9	20k	Resistor, Chip, 1/16-W, 5%	603	Std	Std
5	5	5	5	5	5	5	5	R8, R11–R14	1.5k	Resistor, Chip, 1/16-W, 5%	603	Std	Std
0	0	0	0	1	1	1	1	R10	1.13k	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	1	1	1	0	0	0	0	R10	4.02k	Resistor, Chip, 1/16-W, 1%	603	Std	Std
0	0	0	0	1	1	0	0	R15	137k	Resistor, Chip, 1/16-W, 1%	603	Std	Std
0	0	0	0	1	1	1	1	R16	100k	Resistor, Chip, 1/16-W, 5%	603	Std	Std
1	0	0	0	0	0	0	0	U1	bq24300DSG	IC, Li+ Charger Front-End Protection	DSG8	bq24300DSG	ТІ
0	1	0	0	0	0	0	0	U1	bq24302DSG	IC, Li+ Charger Front-End Protection	DSG8	bq24302DSG	ТІ
0	0	1	0	0	0	0	0	U1	bq24304DSG	IC, Li+ Charger Front-End Protection	DSG8	bq24304DSG	ТІ
0	0	0	1	0	0	0	0	U1	bq24308DSG	IC, Li+ Charger Front-End Protection	DSG8	bq24308DSG	ТІ
0	0	0	0	1	0	0	0	U1	bq24310DSG	IC, Li+ Charger Front-End Protection	DSG8	bq24310DSG	ТІ
0	0	0	0	0	1	0	0	U1	bq24312DSG	IC, Li+ Charger Front-End Protection	DSG8	bq24312DSG	ТІ
0	0	0	0	0	0	1	0	U1	bq24314DSG	IC, Li+ Charger Front-End Protection	DSG8	bq24314DSG	ТІ
0	0	0	0	0	0	0	1	U1	bq24316DSG	IC, Li+ Charger Front-End Protection	DSG8	bq24316DSG	ТІ
1	1	1	1	1	1	1	1	U2	bq24080DRC	IC, Single Chip, Li Ion/Li POL, Charger	DRC10	bq24080DRC	ТІ
1	1	1	1	1	1	1	1	—	HPA245	PCB, 1.2 ln x 3 ln x 0.031 ln		PCB	Any
Not	es:	1. 2.											

OPEN in value column means do not use this component.
 Std in part number column means standard manufacturer's part number

4. Std in MFR column means standard manufacturer

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4.2 Bill of Materials — bq24380/1/14A/15/05

b q 2 4 3	b q 2 4 3	b q 2 4 3	b q 2 4 3	b q 2 4 3						
8 0	8 1	1	1 5	0 5						
- 0	- 0	A -	- 0	- 0						
0 9	1 0	0 1	1 2	1 3						
		1			RefDes	Value	Description	Size	Part Number	MFR
0	0	0	0	1	C1	1 μF	Capacitor, Ceramic, 35-V, X7R, 10%	805	Std	Std
1	1	1	1	1	C2	1 μF	Capacitor, Ceramic, 35-V, X7R, 10%	805	Std	Std
3	3	3	3	3	C3–C5	1 μF	Capacitor, Ceramic, 16-V, X7R, 5%	805	Std	Std
1	1	1	1	1	D1	BZT52C5V1S	Diode, Zener, 200mW, 5.1V	SOD-323	BZT52C5V1S	General
4	4	4	4	4	D2,D3,D5,D6	LTST-C190GKT	Diode, LED, Green, 2.1-V, 20-mA, 6-mcd	603	LTST-C190GKT	Liteon
1	1	1	1	1	D4	LTST-C190CKT	Diode, LED, Red, 1.8-V, 20-mA, 20-mcd	603	LTST-C190CKT	Liteon
3	3	3	3	3	J1, J3, J4	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27×0.25 inch	ED1514	OST
1	1	1	1	1	J2	ED1516	Terminal Block, 4-pin, 6-A, 3.5mm	0.55×0.25 inch	ED1516	OST
8	8	8	8	8	JMP1–JMP8	PTC36SAAN	Header, 2-pin, 100mil spacing, (36-pin strip)	$0.100 \text{ inch} \times 2$	PTC36SAAN	Sullins
8	8	8	8	8	JMP1–JMP8	929950-00	Shorting jumpers, 2-pin, 100mil spacing		929950-00	3M/ESD
0	0	0	0	1	Q1	Si2343DS	MOSFET, Pch, –30 V, 4 A, 53 m Ω	SOT23	Si2343DS	Vishay
0	0	0	0	1	R1	100k	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	1	1	1	0	R2	0	Resistor, Chip, 1/16W, 5%	1206	Std	Std
1	1	1	1	1	R3	20k	Resistor, Chip, 1/16W, 5%	603	Std	Std
0	0	0	0	0	R4	113k	Resistor, Chip, 1/16W, 1%	603	Std	Std
0	0	1	1	0	R5	24.9k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	1	1	1	1	R6	100k	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	1	1	1	1	R7	6.2k	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	1	1	1	1	R9	20k	Resistor, Chip, 1/16W, 5%	603	Std	Std
5	5	5	5	5	R8, R11–R14	1.5k	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	1	1	1	0	R10	1.13k	Resistor, Chip, 1/16W, 1%	603	Std	Std
0	0	0	0	1	R10	4.02k	Resistor, Chip, 1/16W, 1%	603	Std	Std
0	0	0	0	0	R15	137k	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	1	1	1	0	R16	100k	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	0	0	0	0	U1	BQ24380DSG	IC, Li+ Charger Front-End Protection	DSG8	BQ24380DSG	ТІ
0	1	0	0	0	U1	BQ24381DSG	IC, Li+ Charger Front-End Protection	DSG8	BQ24381DSG	TI
0	0	1	0	0	U1	BQ24314ADSG	IC, Li+ Charger Front-End Protection	DSG8	BQ24314ADSG	ТІ
0	0	0	1	0	U1	BQ24315DSG	IC, Li+ Charger Front-End Protection	DSG8	BQ24315DSG	ТΙ
0	0	0	0	1	U1	BQ24305DSG	IC, Li+ Charger Front-End Protection	DSG8	BQ24305DSG	ТΙ
1	1	1	1	1	_	HPA245	PCB, 1.2 ln \times 3 ln \times 0.031 ln		PCB	Any

Notes:

Number 0 in left side columns means do not use this component.
 OPEN in value column means do not use this component.
 Std in part number column means standard manufacturer's part number
 Std in MFR column means standard manufacturer .

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